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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Madhav Datta et al.

Serial No.: 09/961,034

Filed: September 21, 2001

Title: COPPER-CONTAINING C4 BALL-LIMITING METALLURGY STACK FOR
ENHANCED RELIABILITY OF PACKAGED STRUCTURES AND METHOD OF MAKING
SAME

Oct 10 2002
TC 2800 MAIL ROOM Examiner: Long Pham

Group Art Unit: 2823

Docket: 884.522US1

#44/Election
Amor A
10/10/02
AS

RESPONSE TO RESTRICTION REQUIREMENT UNDER 37 C.F.R. § 1.142 AND
PRELIMINARY AMENDMENT UNDER 37 C.F.R. § 1.115

Commissioner for Patents
Washington, D.C. 20231

In response to the Restriction Requirement mailed September 4, 2002, Applicants elect, *without* traverse, Group II (claims 1-11 and 23-28). Applicants note a typographical error in the Office Action, wherein Group II includes claims 13-28. Applicants' review of the claims reveals that it should have stated claims 23-28. Hence, the election set forth above. Applicants cancel remaining claims 12-22 *without* prejudice or disclaimer, and reserves the right to reintroduce them in one or more divisional applications at a later date.

IN THE CLAIMS

Please add new claims 29-39.

29. (New) The BLM stack according to claim 1, wherein the metal adhesion first layer includes a Ti composition, wherein the Ti composition has a thickness in a range from about 500 Å to about 4,000 Å.

30. (New) The BLM stack according to claim 1, wherein the metal second layer includes a NiV composition, and wherein the NiV composition has a thickness in a range from about 500 Å to about 4,000 Å.

31. (New) The BLM stack according to claim 1, wherein the metal second layer includes a NiV composition, and wherein the NiV composition has a thickness in a range from